

**WHAT IS CLAIMED IS:**

1. A polishing composition comprising an abrasive, an acid and/or a salt thereof, and water, wherein copper (Cu) is contained in an amount of 1 mg or less per kg of the polishing composition.  
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2. The polishing composition according to claim 1, wherein the abrasive is colloidal silica.
- 10 3. The polishing composition according to claim 1, which is used for polishing a magnetic disk substrate having Ni element on a surface thereof.
4. A process for reducing a surface defect of a substrate comprising applying to a substrate or a polishing pad a polishing composition comprising an abrasive,  
15 an acid and/or a salt thereof, and water, wherein copper (Cu) is contained in an amount of 1 mg or less per kg of the polishing composition fed to the substrate or the polishing pad.
5. A process for manufacturing a substrate comprising a polishing step  
20 comprising applying to a substrate or a polishing pad a polishing composition comprising an abrasive, an acid and/or a salt thereof, and water, wherein copper (Cu) is contained in an amount of 1 mg or less per kg of the polishing composition fed to the substrate or the polishing pad.
- 25 6. The process according to claim 5, wherein the polishing step is a finishing

step of a surface polishing.